

## N-Channel 800V (D-S) Super Junction Power MOSFET

### PRODUCT SUMMARY

|                           |                        |     |
|---------------------------|------------------------|-----|
| $V_{DS}$ (V)              | 800                    |     |
| $R_{DS(on)}$ ( $\Omega$ ) | $V_{GS} = 10\text{ V}$ | 1.2 |
| $Q_g$ (Max.) (nC)         | 200                    |     |
| $Q_{gs}$ (nC)             | 24                     |     |
| $Q_{gd}$ (nC)             | 110                    |     |
| Configuration             | Single                 |     |

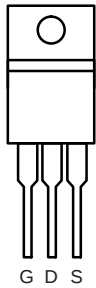
### FEATURES

- Dynamic  $dV/dt$  Rating
- Repetitive Avalanche Rated
- Isolated Central Mounting Hole
- Fast Switching
- Ease of Paralleling
- Simple Drive Requirements
- Compliant to RoHS Directive 2002/95/EC



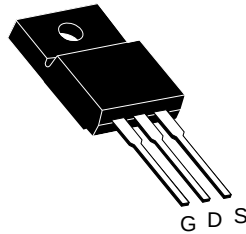
**RoHS\***  
COMPLIANT

TO-220AB



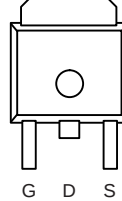
Top View

TO-220 FULLPAK



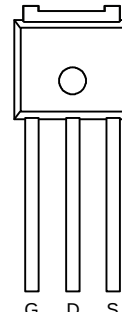
Top View

TO-252

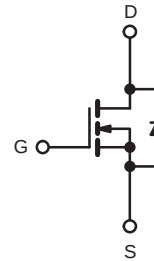


Top View

TO-251



Top View



N-Channel MOSFET

### ABSOLUTE MAXIMUM RATINGS ( $T_C = 25\text{ }^\circ\text{C}$ , unless otherwise noted)

| PARAMETER                                        |                  |                                     | SYMBOL         | LIMIT            | UNIT                  |
|--------------------------------------------------|------------------|-------------------------------------|----------------|------------------|-----------------------|
| Drain-Source Voltage                             |                  |                                     | $V_{DS}$       | 800              | V                     |
| Gate-Source Voltage                              |                  |                                     | $V_{GS}$       | $\pm 20$         |                       |
| Continuous Drain Current                         | $V_{GS}$ at 10 V | $T_C = 25\text{ }^{\circ}\text{C}$  | $I_D$          | 5                | A                     |
|                                                  |                  | $T_C = 100\text{ }^{\circ}\text{C}$ |                | 3.9              |                       |
| Pulsed Drain Current <sup>a</sup>                |                  |                                     | $I_{DM}$       | 21               |                       |
| Linear Derating Factor                           |                  |                                     |                | 1.5              | W/ $^{\circ}\text{C}$ |
| Single Pulse Avalanche Energy <sup>b</sup>       |                  |                                     | $E_{AS}$       | 770              | mJ                    |
| Repetitive Avalanche Current <sup>a</sup>        |                  |                                     | $I_{AR}$       | 7.8              | A                     |
| Repetitive Avalanche Energy <sup>a</sup>         |                  |                                     | $E_{AR}$       | 19               | mJ                    |
| Maximum Power Dissipation                        |                  | $T_C = 25\text{ }^{\circ}\text{C}$  | $P_D$          | 190              | W                     |
| Peak Diode Recovery $dV/dt^c$                    |                  |                                     | $dV/dt$        | 2.0              | V/ns                  |
| Operating Junction and Storage Temperature Range |                  |                                     | $T_J, T_{stg}$ | - 55 to + 150    | $^{\circ}\text{C}$    |
| Soldering Recommendations (Peak Temperature)     |                  | for 10 s                            |                | 300 <sup>d</sup> |                       |
| Mounting Torque                                  | 6-32 or M3 screw |                                     |                | 10               | lbf · in              |
|                                                  |                  |                                     |                | 1.1              | N · m                 |

#### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).  
 b.  $V_{DD} = 50\text{ V}$ , starting  $T_J = 25\text{ }^\circ\text{C}$ ,  $L = 23\text{ mH}$ ,  $R_g = 25\text{ }\Omega$ ,  $I_{AS} = 7.8\text{ A}$  (see fig. 12).  
 c.  $I_{SD} \leq 7.8\text{ A}$ ,  $dI/dt \leq 140\text{ A}/\mu\text{s}$ ,  $V_{DD} \leq 600\text{ V}$ ,  $T_J \leq 150\text{ }^\circ\text{C}$ .  
 d. 1.6 mm from case.

\* Pb containing terminations are not RoHS compliant, exemptions may apply

**THERMAL RESISTANCE RATINGS**

| PARAMETER                           | SYMBOL     | TYP. | MAX. | UNIT |
|-------------------------------------|------------|------|------|------|
| Maximum Junction-to-Ambient         | $R_{thJA}$ | -    | 40   | °C/W |
| Case-to-Sink, Flat, Greased Surface | $R_{thCS}$ | 0.24 | -    |      |
| Maximum Junction-to-Case (Drain)    | $R_{thJC}$ | -    | 0.65 |      |

**SPECIFICATIONS** ( $T_J = 25\text{ }^{\circ}\text{C}$ , unless otherwise noted)

| PARAMETER                                 | SYMBOL              | TEST CONDITIONS                                                                                                                                                    |                                                                                    | MIN. | TYP. | MAX.      | UNIT                |
|-------------------------------------------|---------------------|--------------------------------------------------------------------------------------------------------------------------------------------------------------------|------------------------------------------------------------------------------------|------|------|-----------|---------------------|
| Static                                    |                     |                                                                                                                                                                    |                                                                                    |      |      |           |                     |
| Drain-Source Breakdown Voltage            | $V_{DS}$            | $V_{GS} = 0\text{ V}$ , $I_D = 250\text{ }\mu\text{A}$                                                                                                             |                                                                                    | 800  | -    | -         | V                   |
| $V_{DS}$ Temperature Coefficient          | $\Delta V_{DS}/T_J$ | Reference to $25\text{ }^\circ\text{C}$ , $I_D = 1\text{ mA}$                                                                                                      |                                                                                    | -    | 0.98 | -         | V/ $^\circ\text{C}$ |
| Gate-Source Threshold Voltage             | $V_{GS(th)}$        | $V_{DS} = V_{GS}$ , $I_D = 250\text{ }\mu\text{A}$                                                                                                                 |                                                                                    | 2.0  | -    | 4.0       | V                   |
| Gate-Source Leakage                       | $I_{GSS}$           | $V_{GS} = \pm 20\text{ V}$                                                                                                                                         |                                                                                    | -    | -    | $\pm 100$ | nA                  |
| Zero Gate Voltage Drain Current           | $I_{DSS}$           | $V_{DS} = 800\text{ V}$ , $V_{GS} = 0\text{ V}$                                                                                                                    |                                                                                    | -    | -    | 100       | $\mu\text{A}$       |
|                                           |                     | $V_{DS} = 640\text{ V}$ , $V_{GS} = 0\text{ V}$ , $T_J = 125\text{ }^\circ\text{C}$                                                                                |                                                                                    | -    | -    | 500       |                     |
| Drain-Source On-State Resistance          | $R_{DS(on)}$        | $V_{GS} = 10\text{ V}$                                                                                                                                             | $I_D = 3.7\text{ A}^b$                                                             | -    | 1.2  | -         | $\Omega$            |
| Forward Transconductance                  | $g_{fs}$            | $V_{DS} = 100\text{ V}$ , $I_D = 3.7\text{ A}^b$                                                                                                                   |                                                                                    | 5.6  | -    | -         | S                   |
| Dynamic                                   |                     |                                                                                                                                                                    |                                                                                    |      |      |           |                     |
| Input Capacitance                         | $C_{iss}$           | $V_{GS} = 0\text{ V}$ ,<br>$V_{DS} = 25\text{ V}$ ,<br>$f = 1.0\text{ MHz}$ , see fig. 5                                                                           |                                                                                    | -    | 3100 | -         | pF                  |
| Output Capacitance                        | $C_{oss}$           |                                                                                                                                                                    |                                                                                    | -    | 800  | -         |                     |
| Reverse Transfer Capacitance              | $C_{rss}$           |                                                                                                                                                                    |                                                                                    | -    | 490  | -         |                     |
| Total Gate Charge                         | $Q_g$               | $V_{GS} = 10\text{ V}$                                                                                                                                             | $I_D = 3.8\text{ A}$ , $V_{DS} = 400\text{ V}$ ,<br>see fig. 6 and 13 <sup>b</sup> | -    | -    | 200       | nC                  |
| Gate-Source Charge                        | $Q_{gs}$            |                                                                                                                                                                    |                                                                                    | -    | -    | 24        |                     |
| Gate-Drain Charge                         | $Q_{gd}$            |                                                                                                                                                                    |                                                                                    | -    | -    | 110       |                     |
| Turn-On Delay Time                        | $t_{d(on)}$         | $V_{DD} = 400\text{ V}$ , $I_D = 3.8\text{ A}$ ,<br>$R_g = 6.2\text{ }\Omega$ , $R_D = 52\text{ }\Omega$<br>see fig. 10 <sup>b</sup>                               |                                                                                    | -    | 19   | -         | ns                  |
| Rise Time                                 | $t_r$               |                                                                                                                                                                    |                                                                                    | -    | 38   | -         |                     |
| Turn-Off Delay Time                       | $t_{d(off)}$        |                                                                                                                                                                    |                                                                                    | -    | 120  | -         |                     |
| Fall Time                                 | $t_f$               |                                                                                                                                                                    |                                                                                    | -    | 39   | -         |                     |
| Internal Drain Inductance                 | $L_D$               | Between lead,<br>6 mm (0.25") from<br>package and center of<br>die contact<br> |                                                                                    | -    | 5.0  | -         | nH                  |
| Internal Source Inductance                | $L_S$               |                                                                                                                                                                    |                                                                                    | -    | 13   | -         |                     |
| Drain-Source Body Diode Characteristics   |                     |                                                                                                                                                                    |                                                                                    |      |      |           |                     |
| Continuous Source-Drain Diode Current     | $I_S$               | MOSFET symbol<br>showing the<br>integral reverse<br>p - n junction diode<br>   |                                                                                    | -    | -    | 5.0       | A                   |
| Pulsed Diode Forward Current <sup>a</sup> | $I_{SM}$            |                                                                                                                                                                    |                                                                                    | -    | -    | 21        |                     |
| Body Diode Voltage                        | $V_{SD}$            | $T_J = 25\text{ }^\circ\text{C}$ , $I_S = 3.8\text{ A}$ , $V_{GS} = 0\text{ V}^b$                                                                                  |                                                                                    | -    | -    | 1.8       | V                   |
| Body Diode Reverse Recovery Time          | $t_{rr}$            | $T_J = 25\text{ }^\circ\text{C}$ , $I_F = 3.8\text{ A}$ ,<br>$di/dt = 100\text{ A}/\mu\text{s}^b$                                                                  |                                                                                    | -    | 650  | 980       | ns                  |
| Body Diode Reverse Recovery Charge        | $Q_{rr}$            |                                                                                                                                                                    |                                                                                    | -    | 3.8  | 5.7       | $\mu\text{C}$       |
| Forward Turn-On Time                      | $t_{on}$            | Intrinsic turn-on time is negligible (turn-on is dominated by $L_S$ and $L_D$ )                                                                                    |                                                                                    |      |      |           |                     |

**Notes**

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).  
 b. Pulse width  $\leq 300\text{ }\mu\text{s}$ ; duty cycle  $\leq 2\%$ .

**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)

**Fig. 1 - Typical Output Characteristics,  $T_C = 25\text{ }^{\circ}\text{C}$** 

**Fig. 3 - Typical Transfer Characteristics**

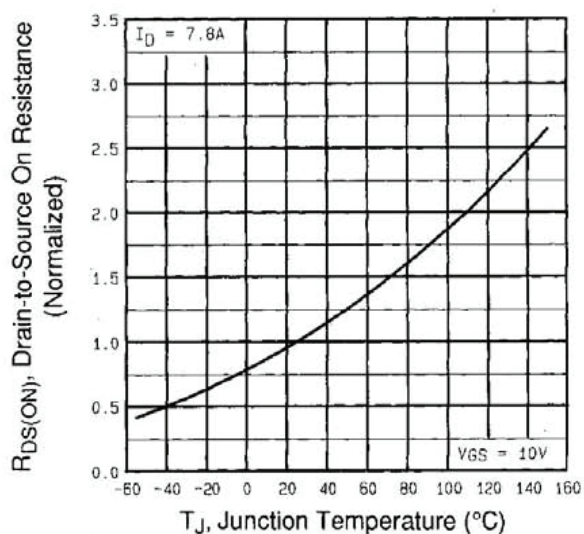
**Fig. 2 - Typical Output Characteristics,  $T_C = 150\text{ }^{\circ}\text{C}$** 

**Fig. 4 - Normalized On-Resistance vs. Temperature**



Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

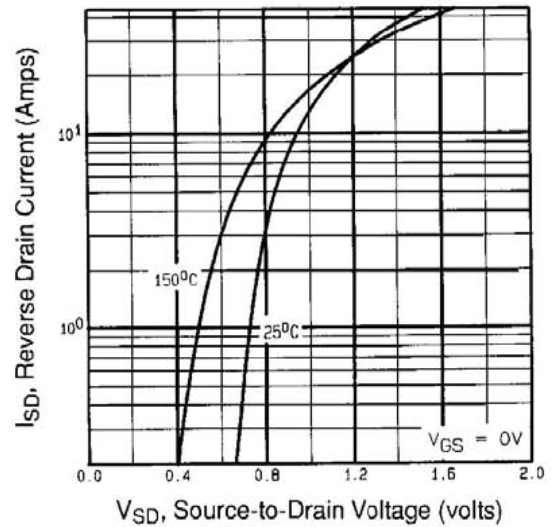


Fig. 7 - Typical Source-Drain Diode Forward Voltage



Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

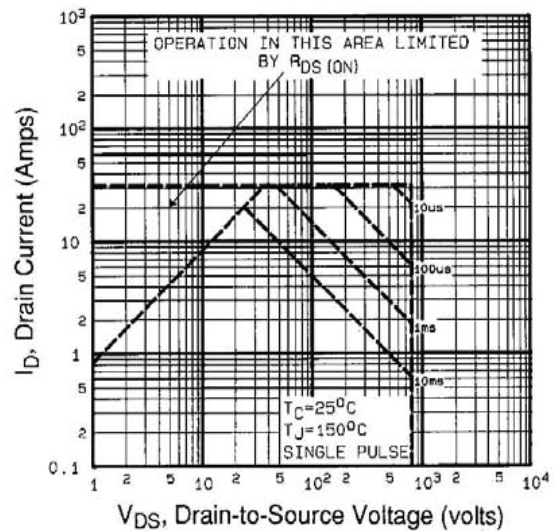


Fig. 8 - Maximum Safe Operating Area

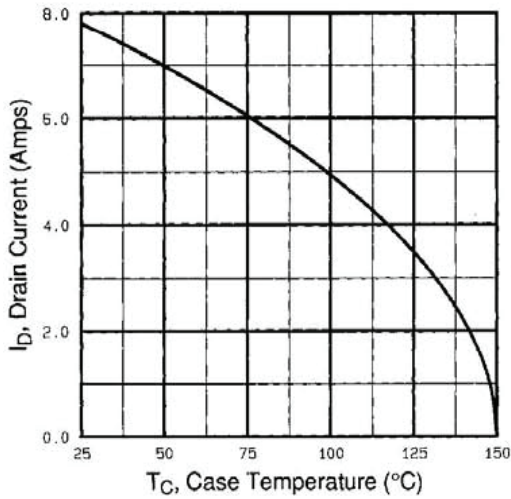


Fig. 9 - Maximum Drain Current vs. Case Temperature

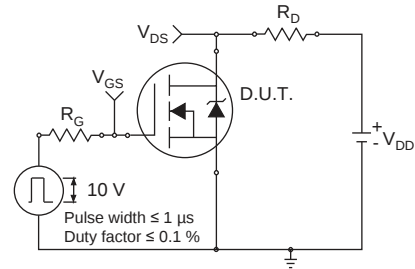


Fig. 10a - Switching Time Test Circuit

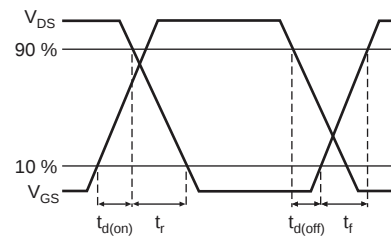


Fig. 10b - Switching Time Waveforms

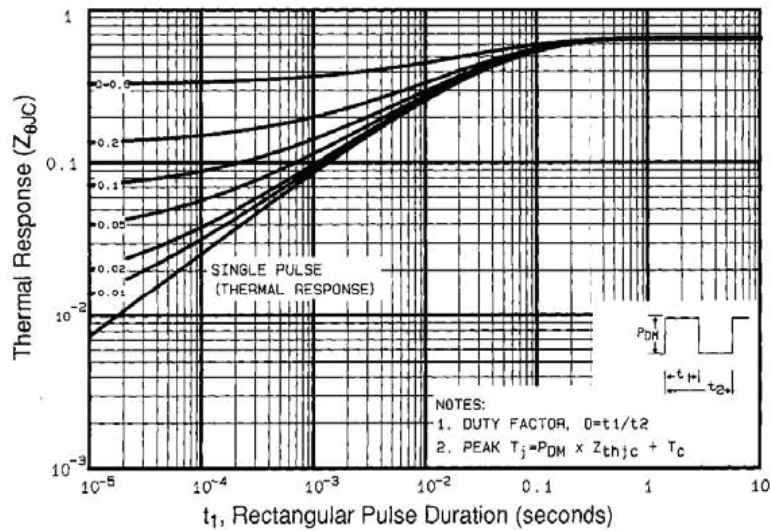


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case



Fig. 12a - Unclamped Inductive Test Circuit

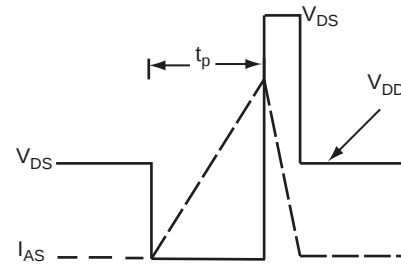


Fig. 12b - Unclamped Inductive Waveforms



Fig. 12c - Maximum Avalanche Energy vs. Drain Current

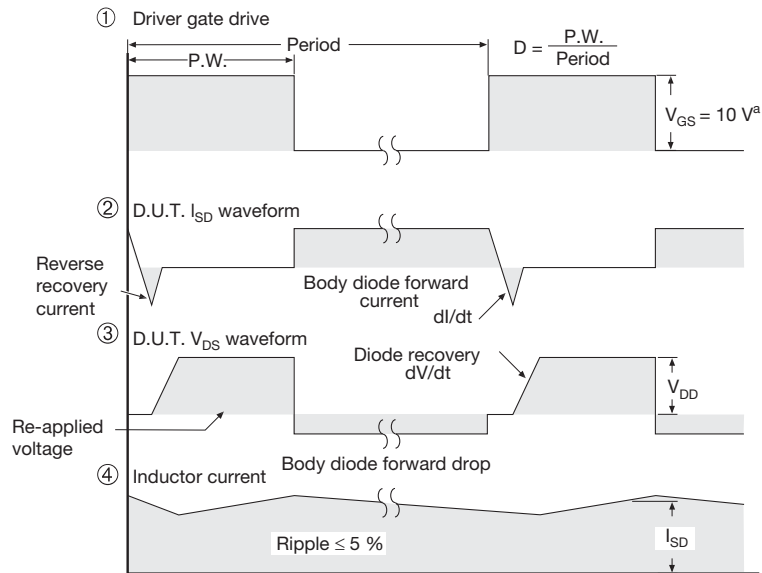
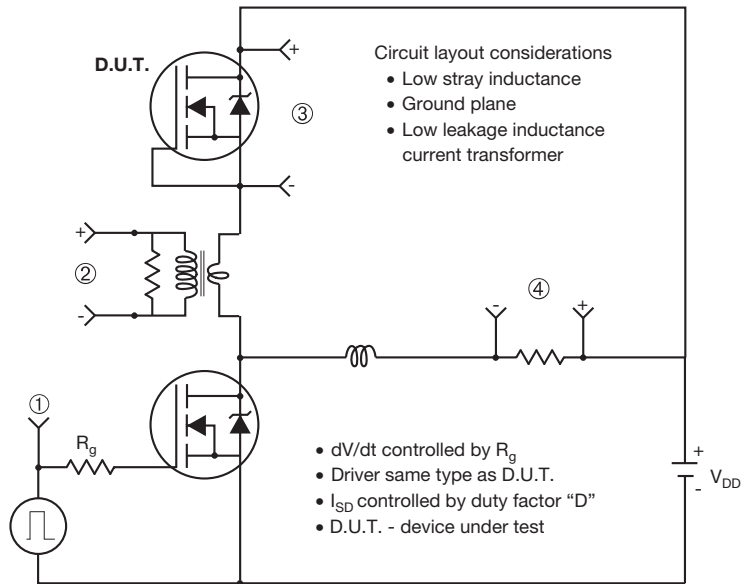


Fig. 13a - Basic Gate Charge Waveform



Fig. 13b - Gate Charge Test Circuit

### Peak Diode Recovery dV/dt Test Circuit

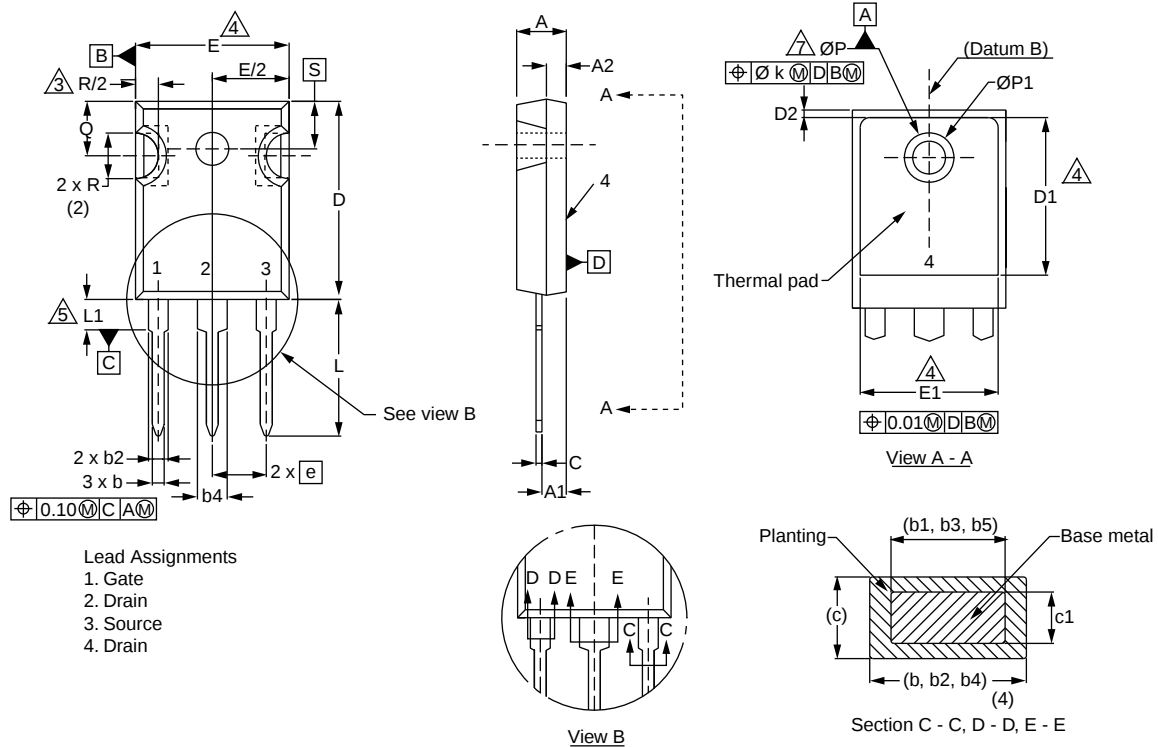


**Note**

a.  $V_{GS} = 5\text{ V}$  for logic level devices

**Fig. 14 - For N-Channel**

## TO-247AC (High Voltage)



| DIM. | MILLIMETERS |       | INCHES |       |
|------|-------------|-------|--------|-------|
|      | MIN.        | MAX.  | MIN.   | MAX.  |
| A    | 4.58        | 5.31  | 0.180  | 0.209 |
| A1   | 2.21        | 2.59  | 0.087  | 0.102 |
| A2   | 1.17        | 2.49  | 0.046  | 0.098 |
| b    | 0.99        | 1.40  | 0.039  | 0.055 |
| b1   | 0.99        | 1.35  | 0.039  | 0.053 |
| b2   | 1.53        | 2.39  | 0.060  | 0.094 |
| b3   | 1.65        | 2.37  | 0.065  | 0.093 |
| b4   | 2.42        | 3.43  | 0.095  | 0.135 |
| b5   | 2.59        | 3.38  | 0.102  | 0.133 |
| c    | 0.38        | 0.86  | 0.015  | 0.034 |
| c1   | 0.38        | 0.76  | 0.015  | 0.030 |
| D    | 19.71       | 20.82 | 0.776  | 0.820 |
| D1   | 13.08       | -     | 0.515  | -     |

| DIM. | MILLIMETERS |       | INCHES    |       |
|------|-------------|-------|-----------|-------|
|      | MIN.        | MAX.  | MIN.      | MAX.  |
| D2   | 0.51        | 1.30  | 0.020     | 0.051 |
| E    | 15.29       | 15.87 | 0.602     | 0.625 |
| E1   | 13.72       | -     | 0.540     | -     |
| e    | 5.46 BSC    |       | 0.215 BSC |       |
| Ø k  | 0.254       |       | 0.010     |       |
| L    | 14.20       | 16.25 | 0.559     | 0.640 |
| L1   | 3.71        | 4.29  | 0.146     | 0.169 |
| N    | 7.62 BSC    |       | 0.300 BSC |       |
| Ø P  | 3.51        | 3.66  | 0.138     | 0.144 |
| Ø P1 | -           | 7.39  | -         | 0.291 |
| Q    | 5.31        | 5.69  | 0.209     | 0.224 |
| R    | 4.52        | 5.49  | 0.178     | 0.216 |
| S    | 5.51 BSC    |       | 0.217 BSC |       |

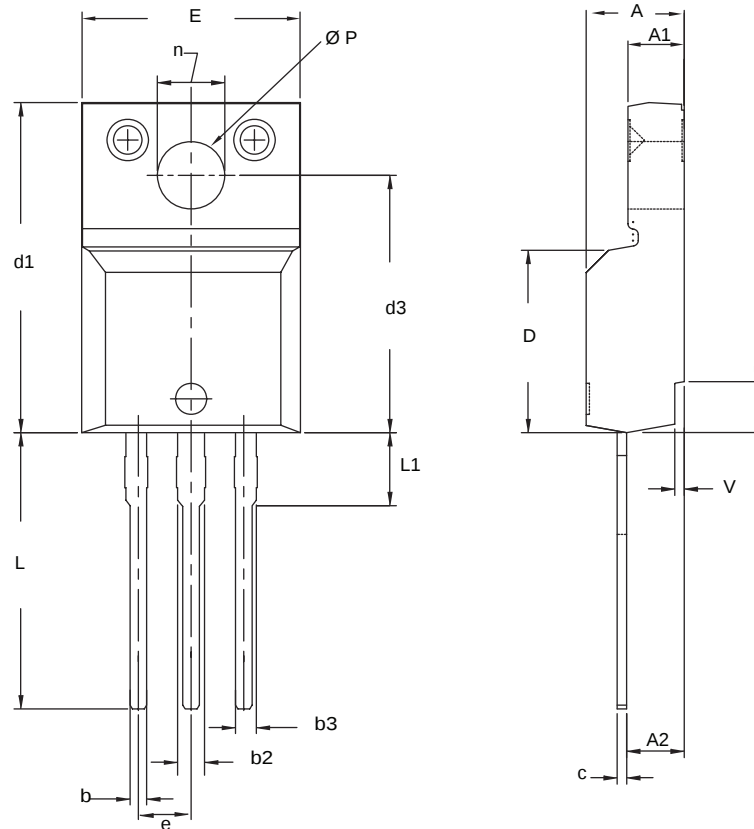
TO-220AB



| DIM. | MILLIMETERS |       | INCHES |       |
|------|-------------|-------|--------|-------|
|      | MIN.        | MAX.  | MIN.   | MAX.  |
| A    | 4.25        | 4.65  | 0.167  | 0.183 |
| b    | 0.69        | 1.01  | 0.027  | 0.040 |
| b(1) | 1.20        | 1.73  | 0.047  | 0.068 |
| c    | 0.36        | 0.61  | 0.014  | 0.024 |
| D    | 14.85       | 15.49 | 0.585  | 0.610 |
| E    | 10.04       | 10.51 | 0.395  | 0.414 |
| e    | 2.41        | 2.67  | 0.095  | 0.105 |
| e(1) | 4.88        | 5.28  | 0.192  | 0.208 |
| F    | 1.14        | 1.40  | 0.045  | 0.055 |
| H(1) | 6.09        | 6.48  | 0.240  | 0.255 |
| J(1) | 2.41        | 2.92  | 0.095  | 0.115 |
| L    | 13.35       | 14.02 | 0.526  | 0.552 |
| L(1) | 3.32        | 3.82  | 0.131  | 0.150 |
| Ø P  | 3.54        | 3.94  | 0.139  | 0.155 |
| Q    | 2.60        | 3.00  | 0.102  | 0.118 |

ECN: X12-0208-Rev. N, 08-Oct-12  
DWG: 5471

**Notes**  
\* M = 1.32 mm to 1.62 mm (dimension including protrusion)  
Heatsink hole for HVM

**TO-220 FULLPAK (HIGH VOLTAGE)**

| DIM. | MILLIMETERS |        | INCHES    |       |
|------|-------------|--------|-----------|-------|
|      | MIN.        | MAX.   | MIN.      | MAX.  |
| A    | 4.570       | 4.830  | 0.180     | 0.190 |
| A1   | 2.570       | 2.830  | 0.101     | 0.111 |
| A2   | 2.510       | 2.850  | 0.099     | 0.112 |
| b    | 0.622       | 0.890  | 0.024     | 0.035 |
| b2   | 1.229       | 1.400  | 0.048     | 0.055 |
| b3   | 1.229       | 1.400  | 0.048     | 0.055 |
| c    | 0.440       | 0.629  | 0.017     | 0.025 |
| D    | 8.650       | 9.800  | 0.341     | 0.386 |
| d1   | 15.88       | 16.120 | 0.622     | 0.635 |
| d3   | 12.300      | 12.920 | 0.484     | 0.509 |
| E    | 10.360      | 10.630 | 0.408     | 0.419 |
| e    | 2.54 BSC    |        | 0.100 BSC |       |
| L    | 13.200      | 13.730 | 0.520     | 0.541 |
| L1   | 3.100       | 3.500  | 0.122     | 0.138 |
| n    | 6.050       | 6.150  | 0.238     | 0.242 |
| Ø P  | 3.050       | 3.450  | 0.120     | 0.136 |
| u    | 2.400       | 2.500  | 0.094     | 0.098 |
| v    | 0.400       | 0.500  | 0.016     | 0.020 |

ECN: X09-0126-Rev. B, 26-Oct-09  
DWG: 5972

**Notes**

1. To be used only for process drawing.
2. These dimensions apply to all TO-220, FULLPAK leadframe versions 3 leads.
3. All critical dimensions should C meet  $C_{pk} > 1.33$ .
4. All dimensions include burrs and plating thickness.
5. No chipping or package damage.

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